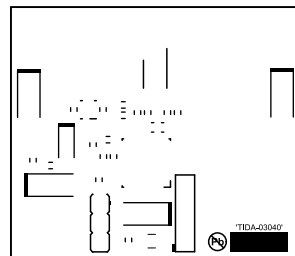
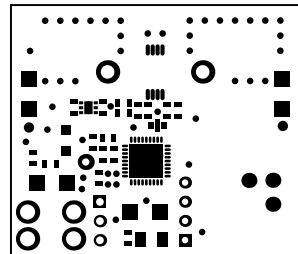


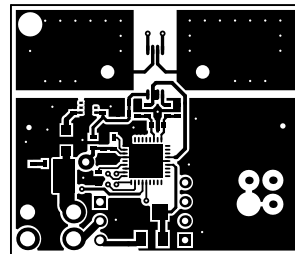
For evaluation only; not FCC approved for resale.



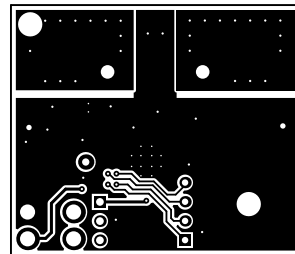
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-03040	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-03040		
PLOT NAME = Top Overlay	GENERATED : 2/27/2017 8:45:43 PM	TEXAS INSTRUMENTS	



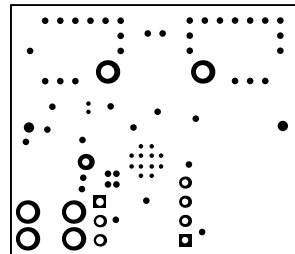
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-03040	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-03040		
PLOT NAME = Top Solder Mask	GENERATED : 2/27/2017 8:45:46 PM	TEXAS INSTRUMENTS	



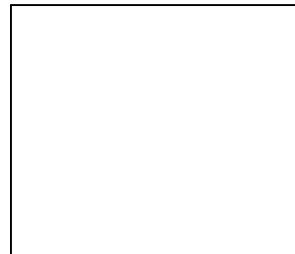
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-03040	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-03040		
PLOT NAME = Top Layer	GENERATED : 2/27/2017 8:45:48 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-03040	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-03040		
PLOT NAME = Bottom Layer	GENERATED : 2/27/2017 8:45:49 PM	TEXAS INSTRUMENTS	

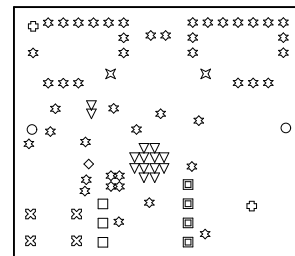


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-03040	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-03040		
PLOT NAME = Bottom Solder Mask	GENERATED : 2/27/2017 8:45:52 PM	TEXAS INSTRUMENTS	

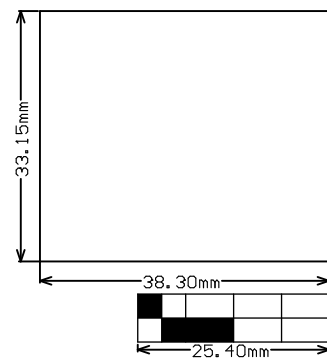


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-03040	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-03040		
PLOT NAME = Bottom Overlay	GENERATED : 2/27/2017 8:45:54 PM		TEXAS INSTRUMENTS

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
▽	14	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
☆	46	11.81mil (0.300mm)	PTH	Round	Top Layer - Bottom Layer	
○	2	28.00mil (0.711mm)	PTH	Round	Top Layer - Bottom Layer	
■	4	33.46mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
◇	1	37.99mil (0.965mm)	PTH	Round	Top Layer - Bottom Layer	
□	3	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	70.87mil (1.800mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	4	78.74mil (2.000mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	102.36mil (2.600mm)	PTH	Round	Top Layer - Bottom Layer	
	78 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-03040	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-03040		
PLOT NAME = Drill Drawing	GENERATED : 2/27/2017	8:45:56 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-03040	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-03040		
PLOT NAME = Board Dimensions	GENERATED : 2/27/2017 8:45:58 PM	TEXAS INSTRUMENTS	



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